2018

August 27-30, 2018
Shenzhen Convention & Exhibition Center
Shenzhen, China

Call for Papers-Technology Conference

The SMTA China cordially invites you to participate in SMTA China South Conference located in Shenzhen 2018. This event, held in conjunction with NEPCON South China 2018, will as usual address the industry's most pressing issues in electronics assembly/ manufacturing, industry/ technology roadmap, business focus, advanced packaging, practical skill development, emerging technologies, and lead-free & reliability.

The Chinese and English version of abstract
Due Date: June 8, 2018
The Chinese and English version of paper
Due Date: July 13, 2018
The Chinese version of PPT
Due Date: July 13, 2018

The paper must be presented in Chinese or English with a translator provied by your side.

30 minutes pure technical papers presented and 5 minutes for answering the question.

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Topical Areas Covered

Advanced Packaging/Components

2.5/3D Packaging and Integration
BGA/CSP
Biomedical Packaging
Component Storage
Connector Technology
Copper Pillars
Copper Wire Bonding
Diffusion Bonding
Embedded and Miniature Passives
Environmental Testing
Failure Analysis Techniques
Flip Chip
High Temperature Packaging
Lead Finishes
Magnetic Soldering
MEMS and Sensors
Moisture Sensitive Devices (MSD)
Package on Package (PoP)
Photonics
Photovoltaics and Solar
Reliability
Silver Wire-bonding
Stacked Die
System in Package (SiP)
Through Silicon Vias (TSVs)
Tin Whiskers
Wafer Level Packaging (WLP)

Assembly

3D Board Assembly
Additive Manufacturing
Adhesive Dispensing
Adhesive Electrically Conductive
Adhesive SMT
Cavity Board Assembly
Cleaning Aqueous
Cleaning Ion Chromatography
Cleaning Resistivity of Solvent Extract
Cleaning Vapor Degreasing
Component Traceability
Design of Experiments
DFX/Design for Six Sigma
Epoxy Electrically Conductive
Head on Pillow Defect/Warpage Induced
Solder Joint Defects
Interconnections Solder
Interconnections Solderless
Low Temperature Processing
Placement 01005 / 03015 Components
Placement BGA/ CSP
Placement Chip Attach to PCB (DCA)
Placement Leadless Area Array Packages
Placement Package-on-Package
Protection Conformal Coating
Protection Low Pressure Molding
Protection Potting
Reflow Pressure Soldering
Reflow Soldering Formic Acid Vapor
Reflow Vacuum Soldering
Reflow Vapor Phase
Rework and Repair of QFNs (01005, Leadless Components, PoP,Rework Reliability)
Solder Paste Jetting
Solder Paste Printing
Solder Paste Stencils
Solder Voiding
Soldering Laser
Soldering Robotic
Soldering Selective
Soldering Wave
Thermo Compression Bonding
Under_ll Dispensing
Under_ll/ Corner Glue/ Other Polymeric Reinforcements
Underfill/ Corner Glue/ Other Polymeric Reinforcements

Business/Supply Chain

Capacity Modeling
Conict Minerals
Contract Manufacturing
Counterfeit Parts
Doing Business in Overseas
Environmental Issues
Lean Manufacturing
Onshoring
Operations Management
Part Obsolescence
RoHS/REACH Compliance
Supplier Management
Technology Roadmaps

Emerging Technologies

<= 0.3mm Pitch Area Array Technologies
3D Circuits
3D Printing & Design Rules
Advanced Packaging
Alternate Solder Alloys
Assembly to Flex Substrates
Assembly to Glass Substrates
Cavity Assembly
Consumer Applications
Embedded Active Technology
Embedded Passive Technology
Flexible Electronics
Halogen and Halogen-Free
High Frequency
Jetting of Solder Pastes
LED Technology/Assembly/Reliability
MEMS/RF/MOEMS
Microsystems Packaging / Modular Microsystems
Nanomaterials
Nanotechnology, Materials, & Electronics
New Materials and Processes
Reliability of Nanodevices
Resin Reinforcement Solder Pastes
Sensors and Manufacturing
Smart Manufacturing Systems
Optoelectronics
Plastic 3D PCB to PCB Technology
Power or Thermal Management
Power Electronics
Printed Electronics Technology
Small Die Size Singulation
Solid State Lighting
Solar Technology
System in a Package
Thermal Interface Materials
Touch Screen Technologies
Virtual Prototyping
Wearable Electronics
Wireless Applications

Harsh Environment Applications

(Military, Aerospace, Automotive, Industrial, Oil & Gas):
Alternate Energy
Battery Prognostics
Components and Reliability
Copper Corrosion
COTS
High Lead Solder Replacement
High Melting Point Solder
High Temperature Electronics
Lead-free Issues
Non-Destructive Inspection
Micro-Computed Tomography
Multiphysics Modeling
Substrates and Finishes
Thermal Management
Tin Whiskers

PCB Technology

Bio-Compatible Substrates
Black Pad and Surface Finish Defects
Conductive Anodic Filament (CAF)
Creep Corrosion
Embedded Passive/Active Components
Halogen Free
HDI
High Power PCBs
Micro-vias (including filled/unfilled)
Moisture Sensitivity
New Laminate Materials
New Surface Finishes & Solderability
Pad Cratering
Soldermask
Substrate Reliability

Process Control

Acoustic Imaging (C-SAM)
Bene-ts of AOI & SPI
CIM
In-Circuit Test
Process Modeling
Software
Test Strategies
Yield Improvement
2D/3D X-Ray

2018

2018年8月27日-30日
深圳会展中心
中国深圳

征集技术论文-华南高科技技术研讨会

中国SMTA诚意的邀请您参加2018年8月27日-30日在深圳举办的SMTA华南高科技会议。此次会议将与第二十四届华南国际电子生产设备暨微电子工业展联合举办，此次会议将涉及行业中最热门的话题，包括电子组装/制造，工业/技术路标，商业焦点，新兴技术，实践技能发展，和无铅及其可靠性。

中英文版本的文章大纲
提交截止日期: 2018年6月8日
中英文版本的技术论文
提交截止日期：2018年7月13日
中文版本的幻灯片形式的演讲稿
提交截止日期: 2018年7月13日

所有技术论文包括文章大纲和演讲者个人简介要求中英文版本刊登在技术论文集中。所有演讲（幻灯片形式的演讲稿）必须为中文并且以中文讲解或英文讲解配备翻译。

30分钟的论文演讲时间和5分钟的回答问题时间

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论文题材涵盖以下关键技术

先进封装及元件

2.5/3D封装和集成
BGA/CSP
生物技术封装
元件存储
连接器技术
铜柱
铜线打线
扩散打线
嵌入及微型被动元件
环境测试
故障分析技术
倒装芯片
耐高温封装
引脚处理
磁力焊接
微型机电系统及传感器
湿度敏感器件
封装堆叠(PoP)
光子学
光伏太阳能
可靠性
银线打线
裸芯片堆叠
系统级封装
穿透硅通孔
锡须
晶圆级封装

装配

3D装配
增材制造
点胶
导电胶
SMT粘胶
空腔基板装配
水洗
离子色谱法
溶剂萃取液的电阻率检测
清洗剂挥发降级
元件可追溯
实验设计
DFX和零缺陷设计
导电环氧树脂
头枕缺陷、翘曲相关锡点缺陷
焊接连接
无焊连接
低温制程
01005／03015元件贴装
BGA/CSP元件贴装
裸芯片贴装
无引脚矩阵封装元件贴装
封装堆叠贴装
敷形涂覆防护
低压成型防护
灌封胶防护
加压回流焊接
甲酸蒸汽回流焊接
真空回流焊接
气相焊接
精密复杂器件返修
锡膏喷涂
锡膏印刷
锡膏印刷模板
焊接空洞
激光焊接
机械手焊接
选择性焊接
波峰焊接
热压打线
底部填充胶点胶
底部填充胶、边角固定胶等
聚合物加固
底部填充、边角固定及聚合物强化

商业与供应链

产能模型
冲突矿产
合同制造
高仿器件
海外业务
环境问题
精益制造
在岸外包
营运管理
器件废除
RoHS/REACH合规
供应商管理
技术路线图

新兴技术

<=0.3mm间距平面阵列技术
3D 电路
3D打印和设计规范
先进封装
替代焊料合金
柔性板装配
玻璃板装配
空腔板装配
消费电子
嵌入式主动技术
嵌入式被动技术
柔性电子
卤素和无卤
高频电子
焊锡膏喷涂
LED技术、装配和可靠性
微机电系统、微光机电系统及射频技术
微系统封装、微系统模组
纳米材料
纳米技术、材料和电子
新材料与制程
纳米器件可靠性
树脂强化锡膏
传感器与制造
智能制造系统
光电子学
塑料3D基板联接
功耗和散热管理
电源电子
印刷电子技术
小型芯片切单
固体照明
太阳能技术
系统级封装
热介质材料
触摸屏技术
虚拟原型机
可穿戴电子
无线电器

环保应用

(军工、航天、汽车、工业、石油天然气):
替代能源
电池剩余电量估算
元件与可靠性
铜腐蚀
商用现货COTS
高铅焊料替代
高熔点焊料
耐高温电子
无铅问题
非破坏性检查
微断层造影技术
多物理场耦合分析模型
基材与表面处理
散热管理
锡须

基板技术

生物相容基材
黑焊盘和表面处理缺陷
导电阳极丝 (CAF)
爬行腐蚀
嵌入式被动、主动元件
无卤
高密度集成HDI
高功率基板
微通孔(包括填充与非填充)
湿度敏感器件
新型层压板材料
新型表面处理和可靠性
焊盘坑裂
阻焊膜
基材可靠性

制程控制

声学成像(C-SAM)
自动光学检查的效益
计算机集成制造(CIM)
ICT在线测试
工艺制程模型
软件
测试策略
良率改善
2D/3D X光检查